

NOTES:

1) MATERIAL:

HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
 INSULATOR: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
 TERMINALS: PHOSPHOR BRONZE, .012/(0.30) THICK
 SHIELD: BRASS, .007/(0.18) THICK

2) FINISH:

TERMINALS:

- A = SELECT GOLD IN CONTACT AREA: 50 MICROINCHES / 1.27 MICROMETERS MIN.,
 *SELECT TIN IN PC TAIL AREA: 100 MICROINCHES / 2.54 MICROMETERS MIN.,
 WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES / 1.27 MICROMETERS MIN.
 B = SELECT GOLD IN CONTACT AREA: 30 MICROINCHES / 0.76 MICROMETERS MIN.,
 *SELECT TIN IN PC TAIL AREA: 100 MICROINCHES / 2.54 MICROMETERS MIN.,
 WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES / 1.27 MICROMETERS MIN.

SHIELD:

- *100 MICROINCHES / 2.54 MICROMETERS NICKEL OVER 50 MICROINCHES /
 1.27 MICROMETERS COPPER UNDERPLATE, PCB GROUND TABS DIPPED IN TIN
 *THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS
 DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
 CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD
 IN THE PC TAILS AND/OR SHIELD.

3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43249.

4) PACKAGING SPECIFICATION:

- UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS
 PER MOLEX PACKAGING SPECIFICATION PK-43249-004.
 UNSHIELDED CONNECTOR ASSEMBLIES PACKAGED IN TUBES
 PER MOLEX PACKAGING SPECIFICATION PK-43249-005.
 SHIELDED CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS
 PER MOLEX PACKAGING SPECIFICATION PK-44050-004.

5) MATES WITH: MODULAR PLUGS THAT CONFORM TO FCC REGULATION PART 68.5.

6) SEE SHEET 3 FOR SHIELDED JACK ASSEMBLY.

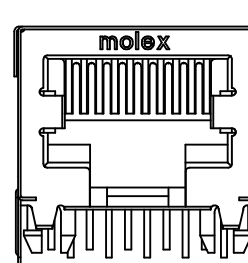
7) SEE SHEETS 5 & 6 FOR P.C. BOARD LAYOUTS.

8) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.

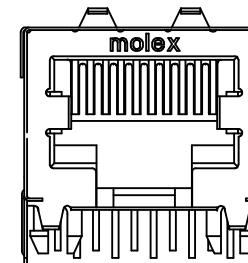
9) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

10) THIS PART CONFORMS TO FCC REGULATION 68.5 AND TIA 1096 FOR MODULAR JACKS.

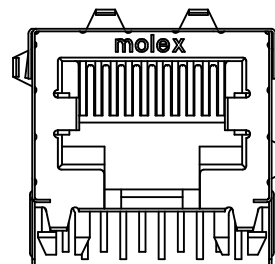
SIDE/TOP GROUND TAB OPTIONS FOR SHIELDS



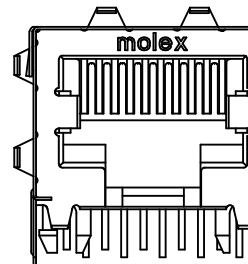
OPTION "A"
NO TOP OR SIDE TABS



OPTION "B"
TOP TABS

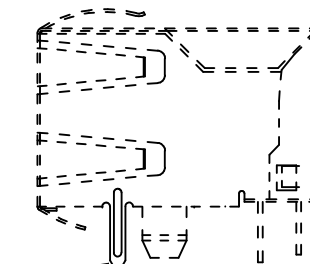


OPTION "C"
TOP AND STAGGERED SIDE TABS

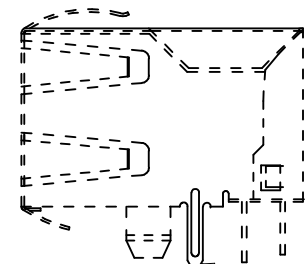


OPTION "D"
TOP AND SIDE TABS

BOTTOM PCB GROUND TAB OPTIONS FOR SHIELDS



OPTION "E"
OPTIONAL FRONT POSITION



OPTION "F"
OPTIONAL REAR POSITION

NOTE: EITHER PCB GROUND TAB OPTION IS AVAILABLE
ON ALL SIDE/TOP TAB CONFIGURATIONS

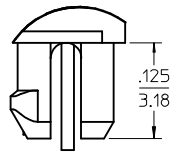
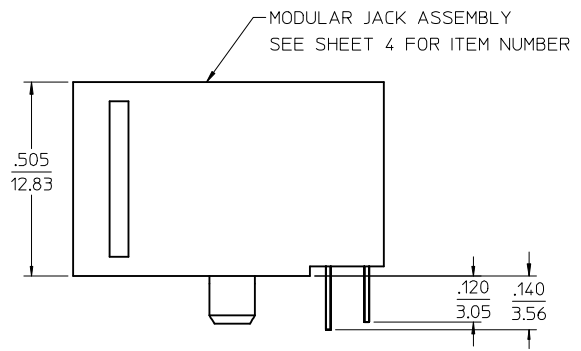
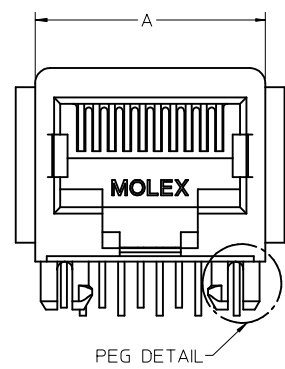
DRAWING LEGEND

- SHEET 1- NOTES, GROUND TAB OPTIONS
 SHEET 2- UNSHIELDED MODULAR JACK
 SHEET 3- SHIELDED MODULAR JACK WITH
 OPTIONAL SIDE/TOP GROUND TABS & BOTTOM GROUND
 TAB WITH OPTIONAL POSITION.
 SHEET 4- PART NUMBER CHARTS
 SHEET 5- FOOTPRINT LAYOUT FOR 8 POSITION HOUSING
 SHEET 6- FOOTPRINT LAYOUT FOR 6 POSITION HOUSING

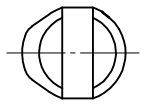
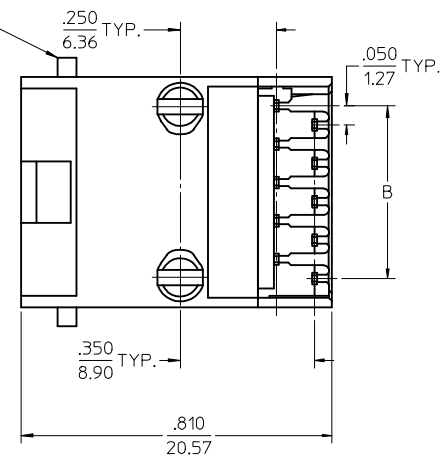
ADDED NOTE 10 EC NO: UCP2009-0740 DRWN: KLOSTERER 2008/09/29 CHKD: JEBELL 2008/10/03 APPR: FSMITH 2008/10/03	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
		▽=0			IN/MM		4:1	INCH			
		▽=0	mm	INCH	DRAWN BY	DATE	TITLE				
			4 PLACES ± --- ± ---	JTR	1993/06/23	LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY					
			3 PLACES ± --- ± .010	CHECKED BY	DATE						
			2 PLACES ± 0.25 ± ---	JTR	1993/06/23						
			1 PLACE ± --- ± ---	APPROVED BY	DATE						
REV		ANGULAR ±1/2°		RAS	1993/06/23	molex MOLEX INCORPORATED					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
				SEE SHEET 4		SDA-43249		1 OF 6			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											

UNSHIELDED MODULAR JACK

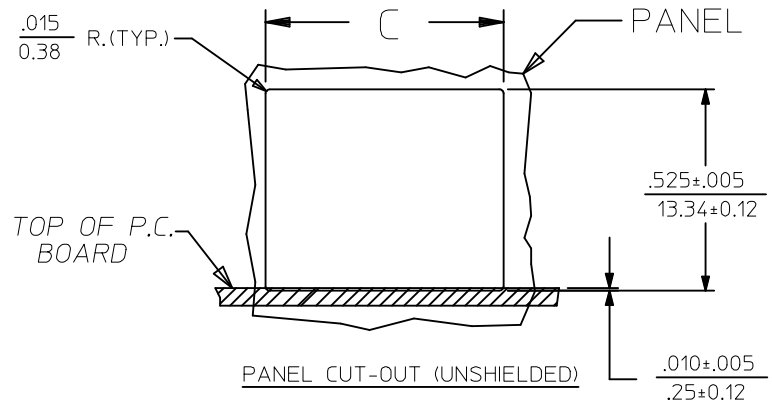
8 POSITION LOADED 10 SIZE SHOWN



OPTIONAL FLANGE
USED FOR FLUSH
MODULAR JACK



PEG DETAIL
SCALE 8:1

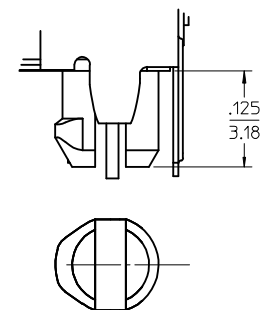
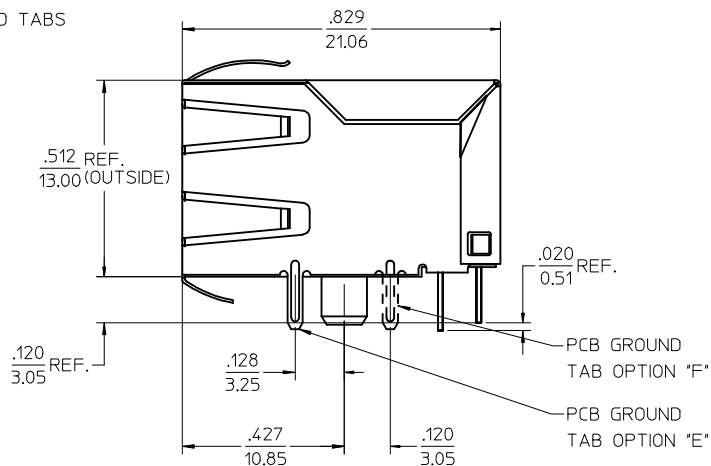
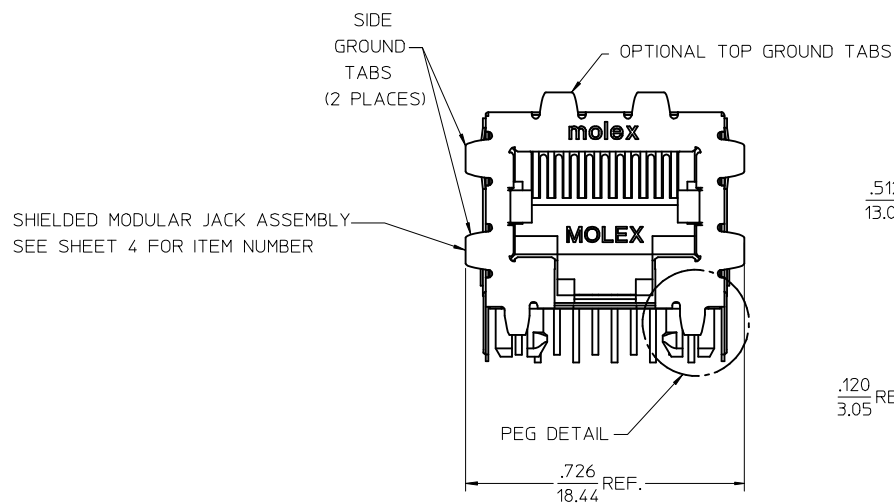


HOUSING SIZE	CIRCUIT SIZE	DIM. A	DIM. B	DIM. C
8	10	.600±.005 (15.24±0.13)	.450±.005 (11.43±0.13)	.620±.005 (15.75±0.13)
8	8	.600±.005 (15.24±0.13)	.350±.005 (8.89±0.13)	.620±.005 (15.75±0.13)
8	4	.600±.005 (15.24±0.13)	.150±.005 (3.81±0.13)	.620±.005 (15.75±0.13)
8	6	.600±.005 (15.24±0.13)	.250±.005 (6.35±0.13)	.620±.005 (15.75±0.13)
6	6	.520±.005 (13.21±0.13)	.250±.005 (6.35±0.13)	.540±.005 (13.72±0.13)
6	4	.520±.005 (13.21±0.13)	.150±.005 (3.81±0.13)	.540±.005 (13.72±0.13)
6	2	.520±.005 (13.21±0.13)	.050±.005 (1.27±0.13)	.540±.005 (13.72±0.13)

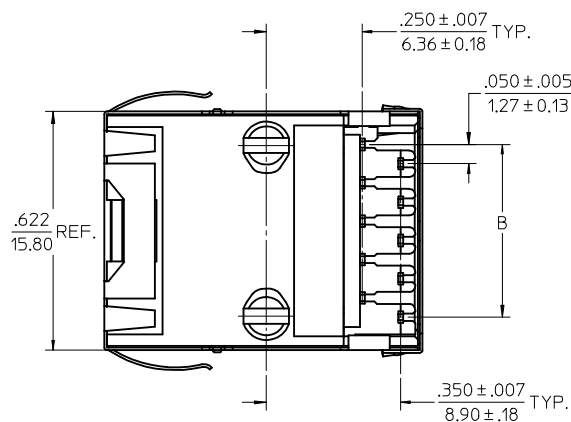
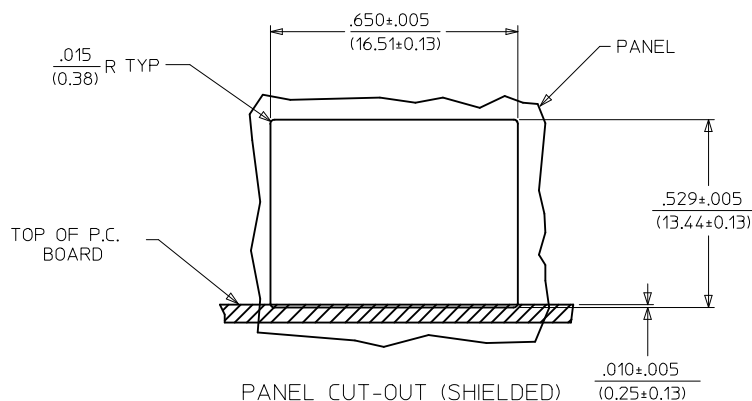
SEE SHEET 1 EC NO: UCP2009-0740 DRWN: JLOSTEME/ER 2008/09/29 CHKD: JBEL 2008/10/03 APPR: FSMITH 2008/10/03	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± ---	3 PLACES ± --- ± .010	DRAWN BY JTR	DATE 1993/06/23	TITLE LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY				
		2 PLACES ± 0.25 ± ---	1 PLACE ± --- ± ---	CHECKED BY JTR	DATE 1993/06/23					
		ANGULAR ± 1/2°		APPROVED BY RAS	DATE 1993/06/23	MATERIAL NO. SDA-43249				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 4						
REV		SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		DOCUMENT NO.		SHEET NO. 2 OF 6		

MODULAR JACK W/ .007" THICK SHIELD AND OPTIONAL GROUND TABS

8 LOADED 10 VERSION SHOWN WITH GROUND TAB OPTIONS "D" AND "E"



PEG DETAIL
SCALE 8:1



DESCRIPTION OF GROUND TAB OPTIONS:
(SEE SHEET 4 FOR AVAILABLE COMBINATIONS OF OPTIONS)

GROUND TAB OPTION	DESCRIPTION
A	NO GROUND TABS
B	TOP TABS ONLY
C	STAGGERED SIDE TABS
D	TOP AND SIDE TABS
E	PCB GROUND TAB IN FRONT POSITION
F	PCB GROUND TAB IN REAR POSITION

HOUSING SIZE	CIRCUIT SIZE	B
8	10	.450 ± .005 11.43 ± 0.13
8	8	.350 ± .005 8.89 ± 0.13

SEE SHEET 1
EC NO: UCP2009-0740
DRWN: JKLOSTEMEIER 2008/09/29
CHKD: JELL 2008/10/03
APPR: FSMITH 2008/10/03

QUALITY SYMBOLS
▽=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES ±	± .010	± .004
3 PLACES ±	± .010	± .004
2 PLACES ±	± .025	± .010
1 PLACE ±	± .050	± .020

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE
MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE
IN/MM

DRAWN BY DATE
JTR 1993/06/23

CHECKED BY DATE
JTR 1993/06/23

APPROVED BY DATE
RAS 1993/06/23

MATERIAL NO.
SEE SHEET 4

SIZE
C

SCALE
4:1

DESIGN UNITS
INCH

THIRD ANGLE PROJECTION

TITLE
LOW PROFILE RIGHT ANGLE
MODULAR JACK ASSEMBLY

MOLEX INCORPORATED

DOCUMENT NO.
SDA-43249

SHEET NO.
3 OF 6

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

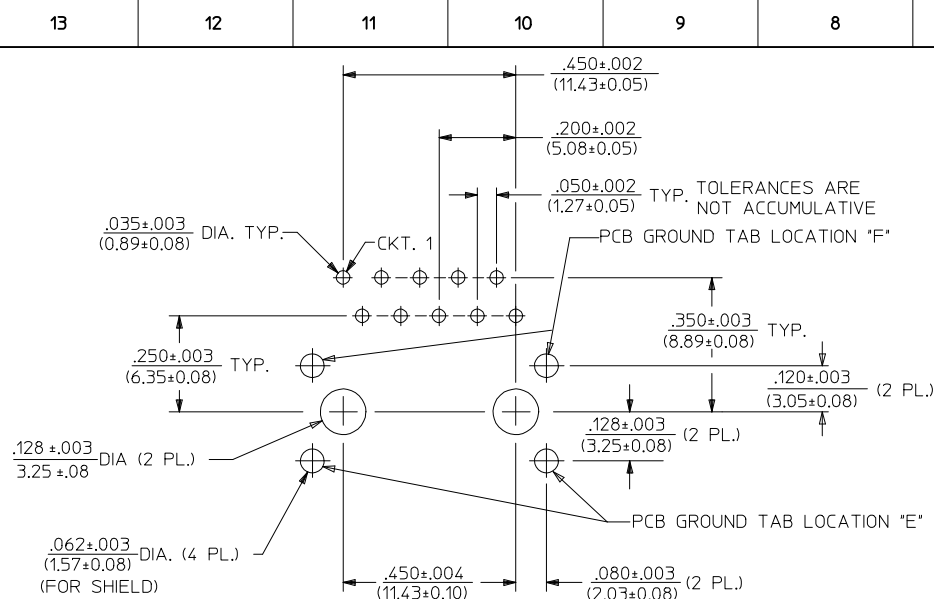
13	12	11	10	9	8	7	6	5	4	3	2	1
FLUSH MOUNT (UNSHIELDED)					SHIELDED, .007" THICK							
ASSEMBLY ITEM NUMBER	CONNECTOR SIZE	NUMBER OF CIRCUITS	TERMINAL PLATING OPTION		ASSEMBLY ITEM NUMBER	CONN. SIZE	NUMBER OF CIRCUITS	TERMINAL PLATING OPTION	SIDE/TOP PANEL GROUND TAB OPTION	PCB GROUND TAB OPTION		PACKAGING OPTION
43249-8001	8	10	A		43249-8900	8	10	A	A	E		TRAY
43249-8004	8	8	A		43249-8901	8	10	A	B	E		TRAY
43249-8010	8	6	A		43249-8902	8	10	A	C	E		TRAY
43249-6001	6	6	A		43249-8903	8	10	A	D	E		TRAY
43249-6004	6	4	A		43249-8908	8	10	A	A	F		TRAY
43249-6007	6	2	A		43249-8909	8	10	A	B	F		TRAY

FLANGELESS (UNSHIELDED)			
ASSEMBLY ITEM NUMBER	CONNECTOR SIZE	NUMBER OF CIRCUITS	TERMINAL PLATING OPTION
43249-8101	8	10	A
43249-8102	8	10	B
43249-8104	8	8	A
43249-8105	8	8	B
43249-8116	8	6	A
43249-8119	8	4	A
43249-6101	6	6	A
43249-6104	6	4	A
43249-6107	6	2	A

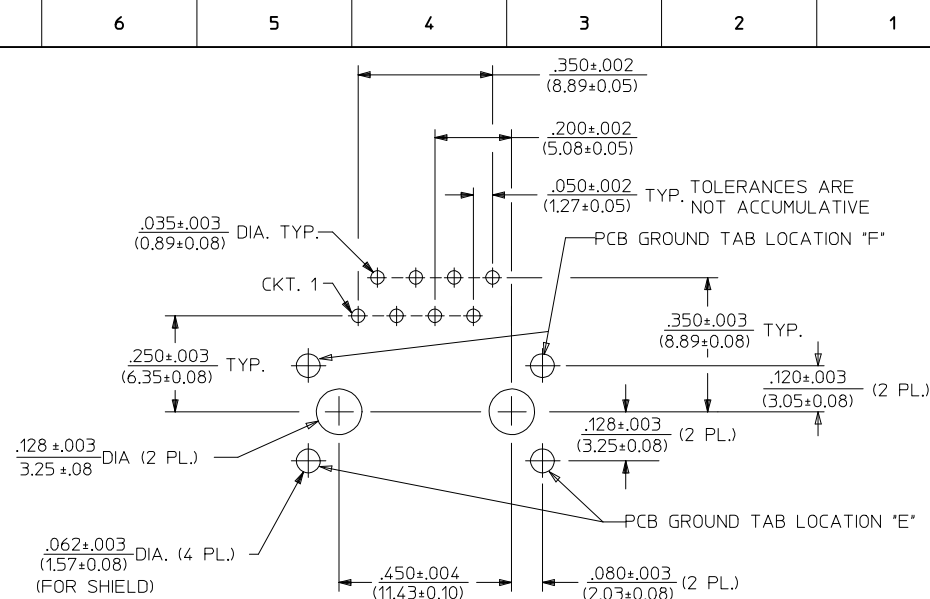
FLANGELESS (UNSHIELDED)			
(SHIPPED IN TUBES)			
43249-6501	6	6	A
43249-6504	6	4	A

SHIELDED, .007" THICK						
ASSEMBLY ITEM NUMBER	CONN. SIZE	NUMBER OF CIRCUITS	TERMINAL PLATING OPTION	SIDE/TOP PANEL GROUND TAB OPTION	PCB GROUND TAB OPTION	PACKAGING OPTION
43249-8900	8	10	A	A	E	TRAY
43249-8901	8	10	A	B	E	TRAY
43249-8902	8	10	A	C	E	TRAY
43249-8903	8	10	A	D	E	TRAY
43249-8908	8	10	A	A	F	TRAY
43249-8909	8	10	A	B	F	TRAY
43249-8910	8	10	A	C	F	TRAY
43249-8911	8	10	A	D	F	TRAY
43249-8916	8	8	A	A	E	TRAY
43249-8917	8	8	A	B	E	TRAY
43249-8918	8	8	A	C	E	TRAY
43249-8919	8	8	A	D	E	TRAY
43249-8920	8	8	B	A	E	TRAY
43249-8924	8	8	A	A	F	TRAY
43249-8925	8	8	A	B	F	TRAY
43249-8926	8	8	A	C	F	TRAY
43249-8927	8	8	A	D	F	TRAY

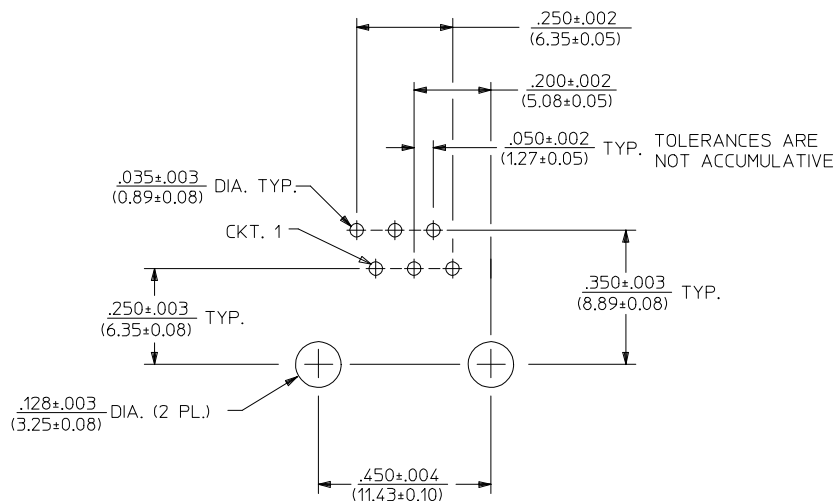
SEE SHEET 1	EC NO: UCP2009-0740		DRWN: JLOSTME IE 2008/09/29		CHKD: JBELL 2008/10/03		APPR: FSWTH 2008/10/03		REV	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1		DESIGN UNITS INCH		THIRD ANGLE PROJECTION 		LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY				
	4 PLACES		± ---		± ---		DRAWN BY JTR					DATE 1993/06/23		TITLE												
	3 PLACES		± ---		± .010		CHECKED BY JTR					DATE 1993/06/23		MOLEX MOLEX INCORPORATED												
	2 PLACES		± 0.25		± ---		APPROVED BY RAS					DATE 1993/06/23		MATERIAL NO.		DOCUMENT NO.		SHEET NO.								
	1 PLACE		± ---		± ---		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					SEE CHART		SDA-43249		4 OF 6										
													ANGULAR ±1/2°													
															SIZE C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									



PC BOARD LAYOUT FOR SIZE 8, 10 CIRCUIT
(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR SIZE 8, 8 CIRCUIT
(COMPONENT SIDE OF BOARD)

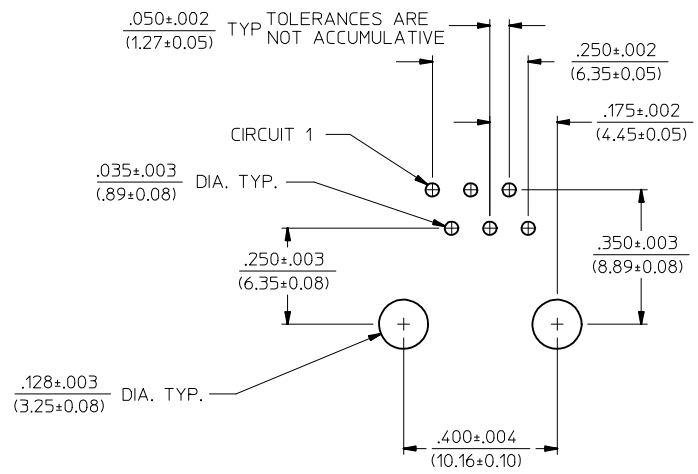


PC BOARD LAYOUT FOR SIZE 8, 6 CIRCUIT
(COMPONENT SIDE OF BOARD)

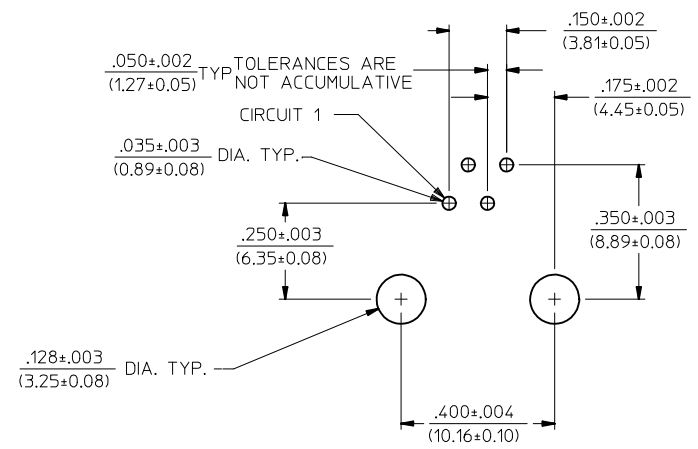
NOTES:
1. RECOMMENDED PCB THICKNESS: .062 ± .005 / (1.57 ± 0.13)

SEE SHEET 1	EC NO: UCP2009-0740	DRWN: JLOSTEMEIER 2008/09/29	CHKD: J.BELL 2008/10/03	APPR: FSMITH 2008/10/03	REV	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	
	K1	▽=0	4 PLACES	± ---			± ---	DRAWN BY	DATE	TITLE LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY					
		▽=0	3 PLACES	± ---			± .010	CHECKED BY	DATE						
		2 PLACES	± 0.25	± ---			JTR	1993/06/23							
		1 PLACE	± ---	± ---			APPROVED BY	DATE							
ANGULAR ±1/2°		RAS	1993/06/23	MOLEX MOLEX INCORPORATED											
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 4		DOCUMENT NO. SDA-43249		SHEET NO. 5 OF 6									
		SIZE C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											

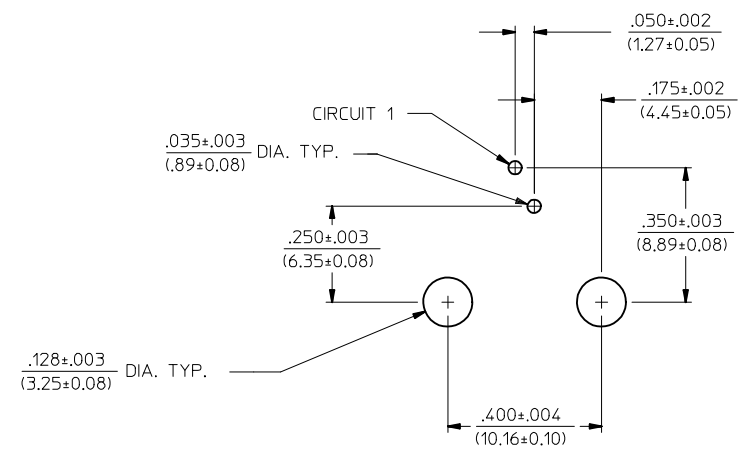
13 12 11 10 9 8 7 6 5 4 3 2 1



PC BOARD LAYOUT FOR SIZE 6, 6 CIRCUIT
(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR SIZE 6, 4 CIRCUIT
(COMPONENT SIDE OF BOARD)



PC BOARD LAYOUT FOR SIZE 6, 2 CIRCUIT
(COMPONENT SIDE OF BOARD)

NOTES:
1. RECOMMENDED PCB THICKNESS: .062±.005/(1.57±0.13)

SEE SHEET 1 EC NO: UCP2009-0740 DRWN: KLOSTEWIEC 2008/09/29 CHKD: J.BELL 2008/10/03 APPR: FSMITH 2008/10/03	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	 THIRD ANGLE PROJECTION
				mm	INCH	DRAWN BY JTR	DATE 1993/06/23	TITLE LOW PROFILE RIGHT ANGLE MODULAR JACK ASSEMBLY	
			4 PLACES	± ---	± ---	CHECKED BY	DATE		
			3 PLACES	± ---	± .010	JTR	1993/06/23		
			2 PLACES	± 0.25	± ---	APPROVED BY	DATE		
			1 PLACE	± ---	± ---	RAS	1993/06/23	 MOLEX INCORPORATED	
			ANGULAR ±1/2°		MATERIAL NO.		DOCUMENT NO.		
K1	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE SHEET 4		SDA-43249			6 OF 6	
			SIZE C	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9